

## TITLE OF THE INVENTION:

## THERMOPLASTIC RESIN COMPOSITION

## BACKGROUND OF THE INVENTION

## 5 Field of the Invention:

The present invention relates to a thermoplastic resin composition high in mechanical strength, excellent in moldability and friction property (sliding wear resistance) and moreover high in anti-blister property at  
10 a high temperature, for example, in the case where soldering is conducted in a reflowing oven.

## Description of the Background Art:

Polyamide 4,6 (nylon 4,6) resins are high in mechanical strength such as modulus in flexure and tensile  
15 elongation and excellent in thermal properties such as heat resistance, electrical properties, friction property, and molding and processing ability and are hence utilized in wide fields such as electric and electronic parts, vehicle parts, various instruments, and sundries.

20 With the miniaturization of products and the improvement in productivity in recent years, the field of electric and electronic industries have come to adopt a method of soldering resinous electronic parts having resin-made parts such as connectors, switches, relays and  
25 coil bobbins to a printed board by a surface-mount technology system.

The term "surface-mount technology system" as used

herein means a mounting system that electronic parts are placed on a printed wiring board through a creamy solder, and the wiring board is then passed through a heating oven (reflowing oven), thereby melting the solder to fix the electronic parts to the wiring board. This surface-mount technology system is different from the conventional insertion-mount system (lead-through system) that lead wires of electronic parts are inserted into through-holes in a wiring board, and soldering (free soldering or wave soldering) is directly conducted on a surface opposite to a surface on which the electronic parts are to be mounted.

This surface-mount technology system has such merits that mount density can be heightened, mounting can be conducted on both surfaces of a board, and production cost can be reduced by high efficiency and is becoming the mainstream of the mount system by soldering.

When electronic parts composed of the conventionally known resin materials including polyamide 4,6 resins are fixed (soldered) to a wiring board by means of the surface-mount technology system, however, such a system involves a problem that blister occurs on the surfaces of the electronic parts when the wiring board, on which the electronic parts have been placed, passes through a reflowing oven, and the commercial value of the resulting product is markedly reduced.

In addition, there is a tendency for frequency of occurrence of blister to increase with the increased oven

temperature (set temperature) required for use of a lead free solder which is favorable from the viewpoint of environmental protection and the like.

Therefore, it is desired to develop a resin composition, which is excellent in anti-blister property when soldering is conducted in a reflowing oven, as a resin material forming resinous electronic parts subjected to the surface-mount technology system.

On the other hand, polyamide resins (hereinafter may also be referred to as "polyamide 9,T resins) obtained by polycondensing 1,9-nonanediamine and terephthalic acid have high mechanical strength (tensile strength and flexural strength) and good heat resistance, and are hence considered to be capable of developing good anti-blister property and expected to be developed into use for the surface-mount technology system.

However, the polyamide 9,T resins are poor in moldability, and so it is difficult to produce thin-wall moldings and the like therefrom. In addition, the polyamide 9,T resins involve a problem that the tensile elongation and the strength of a weld part are poor, and moreover the friction property is also poor.

#### SUMMARY OF THE INVENTION

The present invention has been made on the basis of the foregoing circumstances.

It is the first object of the present invention to

provide a thermoplastic resin composition having excellent anti-blister property , which does not cause blister on the surfaces of resinous parts by passing through a reflowing oven when the resin composition is used as a resin material forming the resinous parts subjected to the surface-mount technology system.

A second object of the present invention is to provide a thermoplastic resin composition high in mechanical strength such as flexural strength, weld strength and tensile elongation and excellent in moldability and friction property .

The present inventors have carried out an extensive investigation with a view toward achieving the above objects. As a result, it has been found that a polyamide 4,6 resin and a polyamide 9,T resin are blended with each other in respective specific proportions, thereby providing a thermoplastic resin composition high in mechanical strength (flexural strength, weld strength and tensile elongation) and excellent in moldability, friction property and anti-blister property . The present invention has been led to completion on the basis of such a finding.

In particular, it has been surprising that the modulus in flexure of the thermoplastic resin composition according to the present invention becomes higher than a value calculated from the blending ratio of the polyamide 4,6 resin to the polyamide 9,T resin.

According to the present invention, there is thus provided a thermoplastic resin composition comprising a polyamide resin component (hereinafter may also be referred to as "specific polyamide resin component")

5 composed of 5 to 95% by weight of the following component (A) and 95 to 5% by weight of the following component (B):

Component (A): a polyamide resin obtained by polycondensing diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s) including  
10 at least adipic acid; and

Component (B): a polyamide resin obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine with dicarboxylic acid(s) including at least terephthalic acid.

15 In the thermoplastic resin composition according to the present invention, the specific polyamide resin component may preferably be composed of 55 to 80% by weight of the component (A) and 45 to 20% by weight of the component (B).

20 In the thermoplastic resin composition according to the present invention, the component (A) may preferably be composed of a polyamide 4,6 resin obtained from tetramethylenediamine and adipic acid.

25 In the thermoplastic resin composition according to the present invention, the component (B) may be preferably be composed of a polyamide resin obtained from 1,9-nonanediamine and/or 2-methyl-1,8-octanediamine, and

terephthalic acid.

The thermoplastic resin composition according to the present invention may preferably comprise, per 100 parts by weight of the specific polyamide resin component, 5 to 70 parts by weight of (C) a flame retardant (hereinafter may also be referred to as "component (C)) and 0 to 50 parts by weight of (D) a flame-retardant aid (hereinafter may also be referred to as "component (D)).

The thermoplastic resin composition according to the present invention may preferably comprise, per 100 parts by weight of the specific polyamide resin component, 5 to 300 parts by weight of (E) an inorganic filler (hereinafter may also be referred to as "component (E)).

#### 15 DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

The thermoplastic resin compositions according to the present invention will hereinafter be described in detail.

##### <Component (A)>

20 The component (A) constituting the thermoplastic resin composition according to the present invention is a polyamide resin obtained by polycondensing diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s) including at least adipic acid and includes (i) "a polyamide 4,6 resin" obtained by polycondensing 25 tetramethylenediamine with adipic acid and (ii) "a copolyamide" comprising a polytetramethylene adipamide

unit as a main constitutive component.

No particular limitation is imposed on the preparation process of the component (A). As examples thereof, may be mentioned the processes described in  
 5 Japanese Patent Application Laid-Open Nos. 149430/1981, 149431/1981, 83029/1983 and 43631/1986.

No particular limitation is also imposed on the degree of polymerization of the component (A). However, the degree of polymerization is preferably such that the  
 10 relative viscosity of the component (A) amounts to a range of 2.0 to 6.0 at a polymer concentration of 1 g/dl in 96% sulfuric acid at 25 °C.

As examples of "other diamines than tetramethylenediamine", which may be used for obtaining the component  
 15 (A), may be mentioned hexamethylenediamine, undecamethylenediamine, dodecamethylenediamine, 2,2,4-trimethylhexamethylenediamine, 2,4,4-trimethylhexamethylenediamine, 5-methylnonamethylenediamine, m-xylylenediamine, p-xylylenediamine, 1,3-bis(aminomethyl)-  
 20 cyclohexane, 1-amino-3-aminomethyl-3,5,5-trimethylcyclohexane, bis(3-methyl-4-aminocyclohexyl)methane, 2,2-bis(4-aminocyclohexyl)propane, 2,2-bis(aminopropyl)piperazine, aminoethylpiperazine, ethylenediamine, propylenediamine and 1,8-octanediamine. These diamines may be used either  
 25 singly or in any combination thereof in combination with tetramethylenediamine.

Among the diamines used for obtaining the component

(A), the proportion of tetramethylenediamine is generally at least 50% by mole, preferably 70 to 100% by mole, more preferably 100% by mole.

As examples of "other dicarboxylic acids than adipic acid", which may be used for obtaining the component (A), may be mentioned aliphatic dicarboxylic acids such as malonic acid, dimethylmalonic acid, succinic acid, 3,3-diethylsuccinic acid, glutaric acid, 2,2-dimethylglutaric acid, 2-methyladipic acid, trimethyladipic acid, pimelic acid, azelaic acid, sebacic acid and suberic acid; alicyclic dicarboxylic acids such as 1,3-cyclopentane-dicarboxylic acid and 1,4-cyclohexanedicarboxylic acid; and aromatic dicarboxylic acids such as terephthalic acid, isophthalic acid, 2,6-naphthalenedicarboxylic acid, 2,7-naphthalenedicarboxylic acid, 1,4-naphthalenedicarboxylic acid, 1,4-phenylenedioxydiacetic acid, 1,3-phenylenedioxydiacetic acid, diphenic acid, 4,4'-oxydibenzoic acid, diphenylmethane-4,4'-dicarboxylic acid, diphenyl-sulfone-4,4'-dicarboxylic acid and 4,4'-biphenyl-dicarboxylic acid. These dicarboxylic acids may be used either singly or in any combination thereof in combination with adipic acid.

Among the dicarboxylic acids used for obtaining the component (A), the proportion of adipic acid is generally at least 50% by mole, preferably 70 to 100% by mole, more preferably 100% by mole.

A polycarboxylic acid having at least 3 functional

groups, such as trimellitic acid, trimesic acid or pyromellitic acid, may be mixed into the reaction system for obtaining the component (A) to introduce units derived from these polycarboxylic acids into the component (A).

5       The amount of such a polycarboxylic acid used is within a range in which moldability by melt molding of the finally obtained resin composition is not impaired.

<Component (B)>

10       The component (B) constituting the thermoplastic resin composition according to the present invention is a polyamide resin obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine with dicarboxylic acid(s) including at least terephthalic acid.

15       As examples of the preparation process of the component (B), may be mentioned the conventionally known polymerization processes for preparing polyamide, i.e., a melt polymerization process, a solution polymerization process, a polymerization process making use of a reaction  
20   type extruder, etc.

Specifically, the polyamide serving as the component (B) can be easily obtained by adding a catalyst and optionally a terminal capping agent at once to a reaction system containing diamine(s) including at least one of  
25   1,9-nonanediamine and 2-methyl-1,8-octanediamine, and dicarboxylic acid(s) including at least terephthalic acid to prepare a nylon salt, preparing a prepolymer having an

intrinsic viscosity  $[\eta]$  of 0.10 to 0.60 dl/g at 30°C in concentrated sulfuric acid once at a temperature not higher than 280°C, and then conducting post polymerization of this prepolymer. As examples of a means for the post  
5 polymerization, may be mentioned solid-state polymerization and polymerization making use of a melt extruder.

The intrinsic viscosity  $[\eta]$  of the prepolymer is controlled within a range of 0.10 to 0.60 dl/g, thereby  
10 preventing deviation of mole balance between carboxyl groups and amino groups and lowering of polymerization speed in the stage of the post polymerization to provide polyamide narrow in molecular weight distribution and excellent in various performance characteristics and  
15 moldability.

When the post polymerization is conducted by the solid-state polymerization, the polymerization is preferably conducted under reduced pressure or an inert gas atmosphere. In addition, the reaction temperature is  
20 controlled within a range of 180 to 280°C, whereby polymerization speed can be accelerated to achieve excellent productivity, and coloring of the resulting polymer and gelation can be effectively prevented.

When the post polymerization is conducted by means  
25 of the melt extruder, the reaction temperature is controlled to at most 370°C, whereby the resulting polyamide is scarcely decomposed to provide the component

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(B) free from deterioration.

As examples of the catalyst which may be used upon the preparation of the polyamide serving as the component (B), may be mentioned phosphoric acid, phosphorous acid and hypophosphorous acid; ammonium salts thereof; metal salts (salts with metals such as potassium, sodium, magnesium, vanadium, calcium, zinc, cobalt, manganese, tin, tungsten, germanium, titanium and antimony) thereof; and esters (ethyl esters, isopropyl esters, butyl esters, hexyl esters, isodecyl esters, octadecyl esters, decyl esters, stearyl esters and phenyl esters) thereof.

The polyamide serving as the component (B) preferably has an intrinsic viscosity  $[\eta]$  within a range of 0.4 to 3.0 dl/g, more preferably 0.6 to 2.0 dl/g, particularly preferably 0.8 to 1.6 dl/g as measured at 30°C in concentrated sulfuric acid.

As examples of "other diamines than 1,9-nonanediamine and 2-methyl-1,8-octanediamine", which may be used for obtaining the component (B), may be mentioned the compounds exemplified as "other diamines than tetramethylenediamine", which may be used for obtaining the component (A). These diamines may be used either singly or in any combination thereof in combination with 1,9-nonanediamine and/or 2-methyl-1,8-octanediamine.

Among the diamines used for obtaining the component (B), the proportion of 1,9-nonanediamine and/or 2-methyl-1,8-octanediamine (total proportion in the case where both

diamines are used) is generally at least 50% by mole, preferably 70 to 100% by mole, more preferably 100% by mole.

As examples of "other dicarboxylic acids than terephthalic acid", which may be used for obtaining the component (B), may be mentioned aliphatic dicarboxylic acids such as adipic acid, malonic acid, dimethylmalonic acid, succinic acid, 3,3-diethylsuccinic acid, glutaric acid, 2,2-dimethylglutaric acid, 2-methyladipic acid, trimethyladipic acid, pimelic acid, azelaic acid, sebacic acid and suberic acid; alicyclic dicarboxylic acids such as 1,3-cyclopentanedicarboxylic acid and 1,4-cyclohexanedicarboxylic acid; and aromatic dicarboxylic acids such as isophthalic acid, 2,6-naphthalenedicarboxylic acid, 2,7-naphthalenedicarboxylic acid, 1,4-naphthalenedicarboxylic acid, 1,4-phenylenedioxydiacetic acid, 1,3-phenylenedioxydiacetic acid, diphenic acid, 4,4'-oxydibenzoic acid, diphenylmethane-4,4'-dicarboxylic acid, diphenylsulfone-4,4'-dicarboxylic acid and 4,4'-biphenyl-dicarboxylic acid.

These dicarboxylic acids may be used either singly or in any combination thereof in combination with terephthalic acid.

Among the dicarboxylic acids used for obtaining the component (B), the proportion of terephthalic acid is generally at least 50% by mole, preferably 70 to 100% by mole, more preferably 100% by mole.

At least one selected from  $\epsilon$ -caprolactam,  $\omega$ -

lauro lactam,  $\zeta$ -enanth lactam,  $\eta$ -capryllactam, etc. may also be mixed into the reaction system for obtaining the component (B).

<Terminal capping agent>

5        Each of the components (A) and (B) constituting the thermoplastic resin composition according to the present invention may be capped at its at least one terminal group with a terminal capping agent.

10        No particular limitation is imposed on the terminal capping agent so far as it is a monofunctional compound having reactivity to the amino group or carboxyl group at the terminal of each polyamide. However, a monocarboxylic acid or a monoamine is preferred from the viewpoints of reactivity and stability to the capped terminal, with the  
15        monocarboxylic acid being more preferred from the viewpoint of easy handling. Besides, an acid anhydride such as phthalic anhydride, monoisocyanate, monofunctional acid halide, monoester, monohydric alcohol or the like may also be used.

20        No particular limitation is imposed on the monocarboxylic acid used as the terminal capping agent so far as it has reactivity to an amino group. As examples thereof, however, may be mentioned aliphatic  
25        monocarboxylic acids such as acetic acid, propionic acid, butyric acid, valeric acid, capronic acid, caprylic acid, lauric acid, tridecylic acid, myristic acid, palmitic acid, stearic acid, pivalic acid and isobutyric acid; alicyclic

monocarboxylic acids such as cyclohexanecarboxylic acid;  
and aromatic monocarboxylic acids such as benzoic acid,  
toluylic acid,  $\alpha$ -naphthalenecarboxylic acid,  $\beta$ -  
naphthalenecarboxylic acid, methyl naphthalenecarboxylic  
5 acid and phenylacetic acid. These acids may be used  
either singly or in any combination thereof.

Among these, acetic acid, propionic acid, butyric  
acid, valeric acid, capronic acid, caprylic acid, lauric  
acid, tridecylic acid, myristic acid, palmitic acid,  
10 stearic acid and benzoic acid are particularly preferred  
from the viewpoints of reactivity, stability to a capped  
terminal, price and the like.

When terminals of polyamide are capped with a  
monocarboxylic acid, it is only necessary to slightly  
15 increase the number of moles of a diamine component used  
to a dicarboxylic acid component upon preparation of the  
polyamide in such a manner that both terminals of the  
resulting polyamide become amino groups, and add the  
monocarboxylic acid as a terminal capping agent.

20 No particular limitation is imposed on the monoamine  
used as the terminal capping agent so far as it has  
reactivity to a carboxyl group. As examples thereof,  
however, may be mentioned aliphatic monoamines such as  
methylamine, ethylamine, propylamine, butylamine,  
25 hexylamine, octylamine, decylamine, stearylamine,  
dimethylamine, diethylamine, dipropylamine and  
dibutylamine; alicyclic monoamines such as cyclohexylamine

and dicyclohexylamine; and aromatic monoamines such as aniline, toluidine, diphenylamine and naphthylamine. These amines may be used either singly or in any combination thereof.

5        Among these, butylamine, hexylamine, octylamine, decylamine, stearylamine, cyclohexylamine and aniline are particularly preferred from the viewpoints of reactivity, boiling point, stability to a capped terminal, price and the like.

10        When terminals of polyamide are capped with a monoamine, it is only necessary to slightly decrease the number of moles of a diamine component used to a dicarboxylic acid component upon preparation of the polyamide in such a manner that both terminals of the  
15        resulting polyamide become carboxyl groups, and add the monoamine as a terminal capping agent.

<Proportions of component (A) and component (B) contained>

Proportions of the components (A) and (B) contained in the thermoplastic resin composition according to the  
20        present invention are controlled to 5-95/95-5, preferably 10-90/90-10, more preferably 40-80/60-20, particularly preferably 55-80/45-20 in terms of "a weight ratio of the component (A) to the component (B)" or (component  
A/component B).

25        Any resin composition in which this ratio is lower than 5/95 is low in mechanical strength such as weld strength and tensile elongation and lacks good moldability

and friction property .

On the other hand, any resin composition in which this ratio exceeds 95/5 lacks good anti-blister property .

Any resin composition in which this ratio falls  
5 within a range of 5/95 to 95/5 has high mechanical strength such as weld strength and tensile elongation, and excellent anti-blister property , moldability and friction property and moreover exhibits a marked improving effect on flexural strength (modulus in flexure) .

10 <Component (C)>

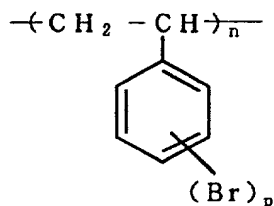
As examples of the component (C) (flame retardant) constituting the thermoplastic resin composition according to the present invention, may be mentioned halogen-containing flame retardants such as bromine-containing  
15 flame retardants, chlorine-containing flame retardants, and phosphorus-containing flame retardants. These flame retardants may be used either singly or in any combination thereof. Among these, the halogen-containing flame retardants are preferred, with the bromine-containing  
20 flame retardants being particularly preferred.

As preferable examples of the bromine-containing flame retardants, may be mentioned brominated polystyrene, brominated poly(phenylene ether) and brominated epoxy oligomers. Brominated polystyrene is particularly  
25 preferred.

As examples of the brominated polystyrene constituting the component (C) , may be mentioned compounds

having a structure represented by the following general formula (1):

General formula (1):



wherein p is an integer of 1 to 5, and n is an integer of 2 or greater.

The brominated polystyrene constituting the component (C) is prepared by a process of polymerizing brominated styrene or a process of brominating polystyrene. The brominated polystyrene obtained by the former process hereinafter may also be referred to as "poly(brominated styrene)", and the brominated polystyrene obtained by the latter process hereinafter may also be referred to as "post-brominated polystyrene".

The content of bromine in the brominated polystyrene is preferably 40 to 75% by weight, more preferably 50 to 75% by weight.

The brominated polystyrene may contain a structural unit derived from a monomer copolymerizable with brominated styrene or styrene as needed.

Examples of such a copolymerizable monomer include ethylene, propylene, butadiene, butene, hexene, pentene, methylbutene, methylpentene, styrene, acrylonitrile, vinyl chloride and vinyl acetate. Among these, ethylene,

propylene, butadiene, styrene and acrylonitrile are preferred.

A functional group-containing vinyl monomer may also be used upon the preparation of the brominated polystyrene.

5 Such a functional group-containing vinyl monomer may be used for copolymerization with brominated styrene or for modification of the terminals or the like of the brominated polystyrene.

As examples of the functional group in the  
10 functional group-containing vinyl monomer, may be mentioned a carboxyl group, an acid anhydride group, an oxazolyl group and an epoxy group.

Specific examples of the functional group-containing vinyl monomer include acrylic acid, methacrylic acid,  
15 maleic acid, maleic anhydride, itaconic anhydride, vinyloxazoline, glycidyl methacrylate and allyl glycidyl ether.

No particular limitation is imposed on the weight average molecular weight ( $M_w$ ) of the brominated  
20 polystyrene constituting the component (C). However, it is preferably 5,000 to 500,000, more preferably 10,000 to 300,000.

The weight average molecular weight ( $M_w$ ) can be determined as a weight average molecular weight in terms  
25 of polystyrene by means of gel permeation chromatography (GPC) in which said brominated polystyrene is dissolved at a concentration of 1 mg/ml in tetrahydrofuran (THF) as a

solvent and measurement is conducted under conditions of a flow rate of 1.0 ml/min and a temperature of 36 to 40°C.

Specific examples of the brominated polystyrene constituting the component (C) are shown in the following

5 Table 1.

Table 1

		Content of Bromine (wt%)	Average Molecular Weight (Mn)	Mw/Mn
C-1	Poly(brominated styrene)  (Polymer of dibromo-styrene)	59	21,000	1.86
C-2	Poly(brominated styrene)  (Copolymer of dibromostyrene: Tribromo- styrene=2:8(wt.))	68	30,000	2.13
C-3	Modified poly(brominated styrene)  (Copolymer of maleic anhydride: dibromostyrene=2: 98(wt.))	60	52,000	1.92
C-4	Post-brominated polystyrene	67	84,000	2.39
C-5	Post-brominated polystyrene	58	32,000	6.12
C-6	Post-brominated polystyrene	59	120,000	3.30

Among the brominated polystyrenes shown in Table 1, C-1, C-2 and C-3, which are poly(brominated styrenes) obtained by polymerizing brominated styrenes, are preferred. When the poly(brominated styrene) is used as the component (C), a far excellent effect (effect as to flame retardance) of the present invention is achieved.

The content of the component (C) in the thermoplastic resin composition according to the present invention is generally 5 to 70 parts by weight, preferably 10 to 60 parts by weight per 100 parts by weight of the specific polyamide resin component composed of the component (A) and the component (B).

If the content of the component (C) is lower than 5 parts by weight, flame resistance, which is an effect brought about by adding the flame retardant, cannot be fully imparted to the resulting resin composition. If the content of the component (C) exceeds 70 parts by weight on the other hand, the mechanical strength, friction property and anti-blister property of the resulting resin composition are lowered.

<Component (D)>

As examples of the component (D) (flame-retardant aid) constituting the thermoplastic resin composition according to the present invention, may be mentioned metallic compounds of Group Va in the periodic table and other metallic compounds.

Examples of the metallic compounds of Group Va in

the periodic table include antimony compounds such as antimony trioxide, antimony pentoxide and sodium antimonate. Examples of the other metallic compounds include boron oxide, zirconium oxide, iron oxide and zinc oxide. These metallic compound may be used either singly or in any combination thereof.

Among these, antimony compounds, which are metallic compounds of Group Va, are preferred, with antimony trioxide being particularly preferred.

The content of the component (D) in the thermoplastic resin composition according to the present invention is generally 0 to 50 parts by weight, preferably 1 to 30 parts by weight per 100 parts by weight of the specific polyamide resin component composed of the component (A) and the component (B). If the content of the component (D) exceeds 50 parts by weight, the mechanical strength of the resulting resin composition is lowered.

<Component (E)>

Examples of the component (E) (inorganic filler) constituting the thermoplastic resin composition according to the present invention include the conventionally known inorganic fillers, for example, various fillers of fibrous, powdery, particulate, plate, needle, cloth and mat forms.

Specific examples of the component (E) include glass fiber, asbestos fiber, carbon fiber, graphite fiber, calcium carbonate, talc, Catalpo, wollastonite, silica,

alumina, silica-alumina, diatomaceous earth, clay, calcined clay, kaolin, mica (fine mica), particulate glass, glass flake, glass balloon (hollow glass), gypsum, red iron oxide, metallic fiber, titanium dioxide, synthetic and natural whiskers such as potassium titanate whisker and aluminum borate whisker, magnesium oxide, calcium silicate, asbestos, sodium aluminate, calcium aluminate, aluminum, aluminum oxide, aluminum hydroxide, copper, stainless steel, zinc oxide and metallic whiskers.

Among these, glass fiber, carbon fiber, kaolin, mica, talc and various kinds of whiskers are preferred in that they are excellent in the effect of improving mechanical strength, with glass fiber, kaolin and talc being particularly preferred from the economical viewpoint.

The inorganic filler used as the component (E) may be subjected to a surface treatment so far as no detrimental influence is thereby imposed on the moldability and physical properties of the thermoplastic resin composition according to the present invention.

Especially, inorganic fillers subjected to treatment with a surface treatment agent such as aminosilane or acrylsilane, or with a film former such as urethane-, acryl- or acrylurethane-compound, etc. may be preferably used.

The content of the component (E) in the thermoplastic resin composition according to the present invention is generally 50 to 300 parts by weight,

preferably 5 to 200 parts by weight, more preferably 5 to 150 parts by weight per 100 parts by weight of the specific polyamide resin component composed of the component (A) and the component (B).

5        If the content of the component (E) is lower than 5 parts by weight, an effect of improving stiffness and dimension stability, which is an effect brought about by adding the filler, cannot be fully imparted to the resulting resin composition. If the content of the  
10    component (E) exceeds 300 parts by weight on the other hand, the weld strength of the resulting resin composition is lowered, and moreover the molding and processing ability of the resin composition is deteriorated.

<Other components>

15        Other optional components than the components (A) to (E) may be added to the thermoplastic resin composition according to the present invention according to required properties and the like so far as no detrimental influence is thereby imposed on the moldability and physical  
20    properties thereof.

As examples of such optional components, may be mentioned pigments, dyes, ultraviolet absorbents, weathering agents, lubricants, nucleating agents, releasing agents, plasticizers, antistatic agents,  
25    hydrophobic zeolite, hydrotalcite and zinc borate.

Antioxidants or heat stabilizers, such as copper compounds such as copper iodide, aromatic amine compounds,

hindered phenol compounds, organophosphorus compounds, and sulfur compounds may be added to the thermoplastic resin composition according to the present invention with a view toward improving the heat resistance thereof.

5       To the thermoplastic resin composition according to the present invention, may be added, as another resin component than the specific polyamide resin component, thermoplastic resins such as PPS, LCP, PPE, polyamide 6, T resins, syndiotactic polystyrene, PET, PBT, polyamide 6, 10 polyamide 66, polyamide 11, polyamide 12, ABS resins, HIPS, AS resins, PS, PTFE, polyvinylidene fluoride, aramide fiber, polyethylene and polypropylene. These thermoplastic resins may be modified by a functional group such as a carboxyl group, acid anhydride group, epoxy 15 group, hydroxyl group, oxazolyl group, amino group or amide group.

As a rubber or elastomer component, may also be added maleic anhydride-modified ethylene-propylene copolymers, hydrogenated butadiene rubber, hydrogenated 20 styrene-butadiene block copolymers, polyester elastomers, polyamide elastomers and/or the like.

#### <Preparation process>

The thermoplastic resin composition according to the present invention can be prepared by melting and kneading 25 the components (A) and (B), and the optionally added components (C) to (E) and other components by means of a kneader.

As examples of the kneader used for preparing the thermoplastic resin composition according to the present invention, may be mentioned extruders, kneaders, rolls, a Brabender, a Banbury mixer and continuous kneaders. These  
5 may be used in combination with each other. Among these, the extruders are preferred, with twin-screw extruders being particularly preferred.

As examples of a method for charging the constitutive components of the thermoplastic resin  
10 composition according to the present invention into the kneader to knead them, may be mentioned (i) a method in which all the components are charged at once to knead them, (ii) a method in which a part of the components are charged at once or in portions to knead them, and the  
15 residual components are then charged at once or in portions to knead them, and (iii) a method in which a part of all the components are charged at once or in portions to knead them, and the residual part of all the components are then charged at once or in portions to knead them.

20 <Molding or forming method>

The thermoplastic resin compositions according to the present invention can be molded or formed by any molding or forming methods, for example, injection molding, compression molding, vacuum forming, sheet forming, film  
25 forming, injection press molding, blow molding, profile extrusion, two-color molding, thermoeject molding, insert molding, outsert molding, etc.

<Use application>

The thermoplastic resin compositions according to the present invention can be used in a wide variety of fields such as electrics and electronics, vehicles, appliances, buildings, sanitary, sports, and sundries owing to their excellent performance. Specific examples thereof include connectors, switches, sensors, sockets, capacitors, jacks, fuse holders, relays, coil bobbins, resistors, housings for IC and LED, gears, bearing retainers, spring holders, chain tensioners, washers, worm wheels, belts, filters, various kinds of housings, autotensioners and wait rollers, breaker parts, and clutch parts. Among these, the thermoplastic resin compositions according to the present invention are particularly useful for connectors, switches, sensors, resistors, relays, capacitors, sockets, jacks, fuse holders, coil bobbins and housings for IC and LED, to which the surface-mount technology system is applied.

(Examples)

The present invention will hereinafter be described in more detail by the following examples and comparative examples. However, the present invention is not limited to these examples.

All designations of "%" and "part" or "parts" as will be used in these examples and comparative examples mean "% by weight" and "part or parts by weight" unless expressly noted.

## [Preparation Example A1]

A polyamide 4,6 resin obtained by polycondensing 1,4-tetramethylenediamine with adipic acid was provided as Component (A). This resin was regarded as "Component (A-1)".

Component (A-1) had a relative viscosity of 2.5 as measured at a polymer concentration of 1 g/dl (25°C) in 96% sulfuric acid and a crystal melting temperature (a temperature corresponding to a peak upon melting of crystals by DSC measurement; the same shall apply hereinafter) of 300°C.

## [Preparation Example A2]

A polyamide 4,6 resin having a different of degree polymerization from Component (A-1) was provided as Component (A). This resin was regarded as "Component (A-2)".

Component (A-2) had a relative viscosity of 3.5 as measured at a polymer concentration of 1 g/dl (25°C) in 96% sulfuric acid and a crystal melting temperature of 300°C.

## [Preparation Example A3]

A polyamide 4,6 resin having a different degree of polymerization from Component (A-1) and Component (A-2) was provided as Component (A). This resin was regarded as "Component (A-3)".

Component (A-3) had a relative viscosity of 4.5 as measured at a polymer concentration of 1 g/dl (25°C) in

96% sulfuric acid and a crystal melting temperature of 300°C.

[Preparation Example B1]

5 A polyamide 9,T resin obtained by polycondensing 1,9-nonanediamine with terephthalic acid and benzoic acid (terminal capping agent) was provided as Component (B). This resin was regarded as "Component (B-1)".

10 Component (B-1) had an intrinsic viscosity  $[\eta]$  of 1.15 as measured at 30°C in concentrated sulfuric acid and a crystal melting temperature of 315°C.

[Preparation Example B2]

15 A polyamide resin obtained by polycondensing a diamine component composed of 85% by mole of 1,9-nonanediamine and 15% by mole of 2-methyl-1,8-octanediamine with terephthalic acid and benzoic acid (terminal capping agent) was provided as Component (B). This resin was regarded as "Component (B-2)".

20 Component (B-2) had an intrinsic viscosity  $[\eta]$  of 1.15 as measured at 30°C in concentrated sulfuric acid and a crystal melting temperature of 306°C.

[Preparation Example C1]

25 Poly(brominated styrene), "PDBS-80" (product of Great Lakes Chemical Co.; bromine content: 59%,  $M_n = 2,100$ ,  $M_w/M_n = 1.86$ ) was provided as Component (C) (flame retardant).

[Preparation Example D1]

Antimony trioxide was provided as Component (D)

(flame-retardant aid).

[Preparation Example E1]

Glass fiber-chopped strand having a fiber diameter of 10  $\mu\text{m}$  and a cut length of 3 mm and subjected to a surface treatment (surface treating agent: aminosilane, greige goods: urethane) was provided as Component (E).  
<Examples 1 to 6, and Comparative Examples 1 and 2>

After Components (A), (B), (C) and (D) were uniformly mixed by means of a tumbler in accordance with their corresponding formulations shown in the following Table 3, each of the mixtures was fed to a twin-screw extruder (screw diameter: 44 mm) having a feed opening in the middle thereof, from the proximal part thereof, and Component (E) was fed from the feed opening provided in the middle thereof to melt and knead the respective components while venting under reduced pressure, thereby forming pellets.

The pellets thus obtained were fully dried by a dehumidifying dryer and molded into prescribed specimens (specimens for performance evaluation) by means of an injection molding machine.

<Example 7, and Comparative Examples 3 and 4>

After Components (A) and (B) were uniformly mixed by means of a tumbler in accordance with their corresponding formulations shown in the following Table 3, each of the mixtures was fed to the twin-screw extruder (screw diameter: 44 mm) from the proximal part thereof, the

respective components were melt and knead while venting under reduced pressure, thereby forming pellets.

The pellets thus obtained were fully dried by a dehumidifying dryer and molded into prescribed specimens (specimens for performance evaluation) by means of an injection molding machine.

<Evaluation of resin composition>

With respect to each of the resin compositions according to the present invention obtained in Examples 1 to 7 and the resin compositions for comparison obtained in Comparative Examples 1 to 4, the mechanical strength (modulus in flexure, weld strength and tensile elongation) was measured, and anti-blister property, moldability and friction property were evaluated. The results are shown collectively in Table 3.

Incidentally, the measurement and evaluation were conducted in accordance with the following respective methods:

(1) Modulus in flexure:

Measured in accordance with ASTM D 790.

(2) Weld strength:

A molding a (two gates at both ends) in the form of a bar of a wall thickness of 0.8 mm, having a welded part at the central portion thereof and a molding b (one gate at an end) in the form of a bar of a wall thickness of 0.8 mm having no welded part were produced.

With respect to each of the moldings a and b thus

obtained, an indenter was applied to the central part (the welded part in the molding a) thereof to measure flexural strength, and a retention (%) was calculated out from the following equation to regard it as the weld strength.

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$$\text{Retention (\%)} = (\text{Flexural strength of Molding a} / \text{Flexural strength of Molding b}) \times 100$$

(3) Tensile elongation:

Measured in accordance with ASTM D 638.

10 (4) Anti-blister property :

(i) Specimen:

A flat plate having a thickness of 0.8 mm was obtained by means of an injection molding machine and then left to stand for 48 hours under an environment of a temperature of 35°C and a relative humidity of 90% to cause the flat plate to absorb water (moisture), thereby providing a specimen.

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(ii) Conditions for reflow test:

"Air Reflow AIS-260" (manufactured by Eitec Techtron Co.) was used as a reflowing apparatus.

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The temperature of the reflowing apparatus was preset as shown in the following Table 2. In Table 2, "PH1", "PH2" and "PH3" mean preset temperatures in reflow preheating zones, and "RE" means a preset temperature in a reflowing zone.

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Table 2

	Reflow Preheating Temperature (°C)			Reflow Temperature (°C)
	PH1	PH2	PH3	RE
Condition 1	200	180	190	280

## (iii) Evaluation:

- 5           The number of blisters occurred in the specimen was counted.

## (5) Moldability:

- "Arplug 270-90-350D" was used as an injection molding machine to charge each thermoplastic resin composition sample into a cavity (0.67 mm x 12.7 mm x 127 mm) of a mold, thereby ranking the moldability of the sample as "A" where the sample was surely charged, or "B" where the sample was insufficiently charged. The cylinder temperature and injection pressure of the injection molding machine were preset to 315°C and 65%, respectively, and the mold temperature was preset to 120°C.

## (6) Friction property :

- "Suzuki type fractional wear tester" was used, and carbon steel (S45C) was provided as the fellow material to conduct a sliding test under conditions of a surface pressure of 0.1 MPa, a speed of 50 cm/sec and a travel distance of 20 km to measure a specific abrasion loss (mm<sup>3</sup>/N·km) of a test sample.





From the results shown in Table 3, the following facts are understood.

(1) Examples 1 to 6, and Comparative Examples 1 and 2:

The resin compositions according to Examples 1 to 6 contained the specific polyamide resin component composed of the component (A) and the component (B) blended with each other in specific ranges and are hence high in mechanical strength (modulus in flexure, weld strength and tensile elongation) and excellent in anti-blister property, moldability and friction property

To the contrary, the resin composition according to Comparative Example 1 is low in modulus in flexure and poor in anti-blister property because the content of the component (A) is too high, and the content of the component (B) is too low.

Further, the resin composition according to Comparative Example 2 is low in mechanical strength and poor in moldability and friction property because the content of the component (A) is too low, and the content of the component (B) is too high.

(2) Example 7, and Comparative Examples 3 and 4:

The resin composition according to Example 7 was composed of the specific polyamide resin composed of the component (A) and the component (B) blended with each other in specific ranges and are hence high in mechanical strength (modulus in flexure, weld strength and tensile elongation) and excellent in anti-blister property,

moldability and friction property.

To the contrary, the resin composition according to Comparative Example 3 is low in modulus in flexure and poor in anti-blister property because the content of the component (A) is too high, and the content of the component (B) is too low.

Further, the resin composition according to Comparative Example 4 is low in mechanical strength and poor in moldability and friction property because the content of the component (A) is too low, and the content of the component (B) is too high.

<Effect of the invention>

As described above, the thermoplastic resin compositions according to the present invention have excellent anti-blister property , and do not cause blister on the surfaces of resinous parts molded therefrom by passing through a reflowing oven when the resin composition is used as a resin material forming the resinous parts subjected to the surface-mount technology system.

Further, the thermoplastic resin compositions according to the present invention are high in mechanical strength such as flexural strength, weld strength and tensile, elongation and excellent in moldability and friction property.